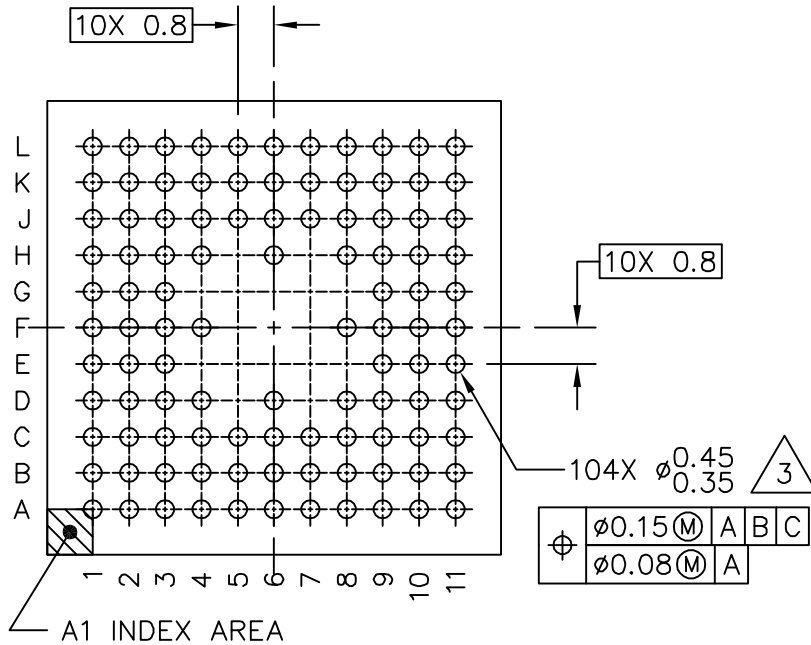
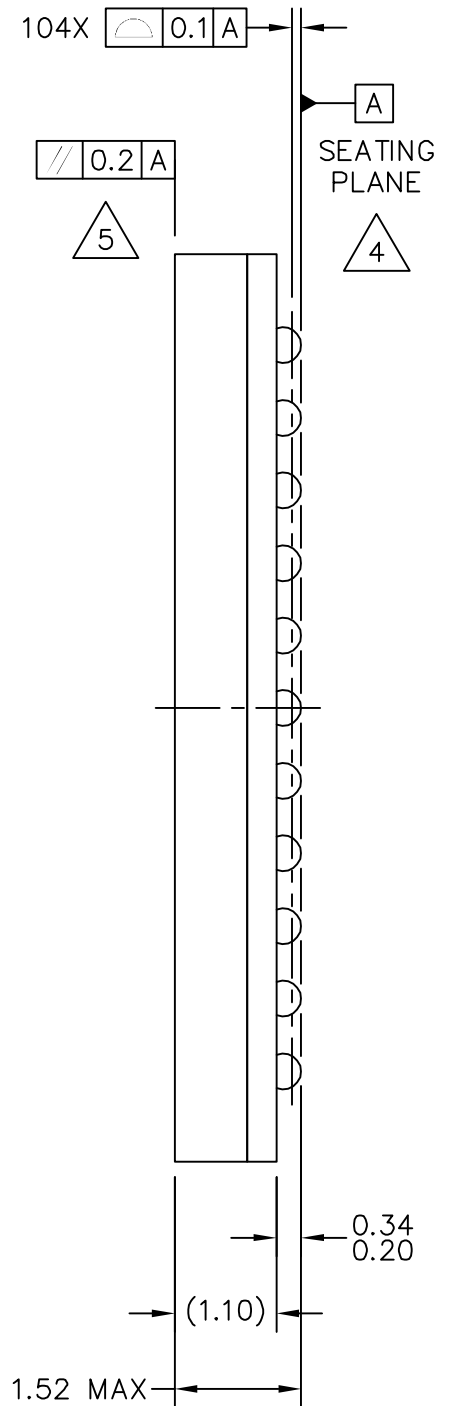


TOP VIEW



BOTTOM VIEW



SIDE VIEW

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TITLE: PBGA, LOW PROFILE, FINE PITCH, 104 I/O, 10 X 10 PKG, 0.8 MM PITCH (MAP)	DOCUMENT NO: 98ARH98267A	REV: C
	STANDARD: JEDEC M0275	
	SOT1544-1	24 DEC 2015



NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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